

## 2SK1416-VB Datasheet

### N-Channel 60 V (D-S) MOSFET

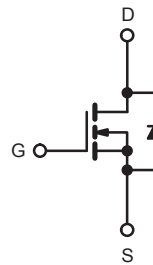
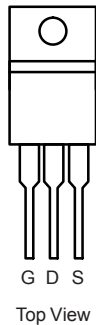
PRODUCT SUMMARY		
$V_{DS}$ (V)	$R_{DS(on)}$ ( $\Omega$ )	$I_D$ (A) <sup>a</sup>
60	0.024 at $V_{GS} = 10$ V	50
	0.028 at $V_{GS} = 4.5$ V	40

**FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- Surface Mount
- Available in Tape and Reel
- Dynamic  $dV/dt$  Rating
- Logic-Level Gate Drive
- Fast Switching
- Compliant to RoHS Directive 2002/95/EC


**RoHS\***  
 COMPLIANT

TO-220AB



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ( $T_C = 25$ °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		$V_{DS}$	60	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	
Continuous Drain Current <sup>f</sup>	$V_{GS}$ at 10 V	$I_D$	$T_C = 25$ °C	A
Continuous Drain Current			$T_C = 100$ °C	
Pulsed Drain Current <sup>a</sup>		$I_{DM}$	200	
Linear Derating Factor			1.0	W/°C
Linear Derating Factor (PCB Mount) <sup>e</sup>			0.025	
Single Pulse Avalanche Energy <sup>b</sup>		$E_{AS}$	400	mJ
Maximum Power Dissipation	$T_C = 25$ °C	$P_D$	150	W
Maximum Power Dissipation (PCB Mount) <sup>e</sup>	$T_A = 25$ °C		3.7	
Peak Diode Recovery $dV/dt^c$		$dV/dt$	4.5	V/ns
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	- 55 to + 175	°C
Soldering Recommendations (Peak Temperature) <sup>d</sup>	for 10 s		300 <sup>d</sup>	

**Notes**

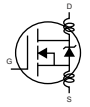

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = 25$  V, starting  $T_J = 25$  °C,  $L = 179$   $\mu$ H,  $R_g = 25$   $\Omega$ ,  $I_{AS} = 51$  A (see fig. 12).
- $I_{SD} \leq 51$  A,  $di/dt \leq 250$  A/ $\mu$ s,  $V_{DD} \leq V_{DS}$ ,  $T_J \leq 175$  °C.
- 1.6 mm from case.
- When mounted on 1" square PCB (FR-4 or G-10 material).
- Current limited by the package, (die current = 51 A).

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	$R_{thJA}$	-	62	°C/W
Maximum Junction-to-Ambient (PCB Mount) <sup>a</sup>	$R_{thJA}$	-	40	
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	1.0	

**Note**

a. When mounted on 1" square PCB (FR-4 or G-10 material).

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SPECIFICATIONS ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
<b>Static</b>							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0, I_D = 250\ \mu\text{A}$	60	-	-	V	
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}$ , $I_D = 1\ \text{mA}$	-	0.070	-	V/°C	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	1.0	-	2.5		
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 10\ \text{V}$	-	-	$\pm 100$	nA	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 60\ \text{V}, V_{GS} = 0\ \text{V}$	-	-	25	$\mu\text{A}$	
		$V_{DS} = 48\ \text{V}, V_{GS} = 0\ \text{V}, T_J = 150\text{ }^\circ\text{C}$	-	-	250		
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10\ \text{V}$	$I_D = 21\ \text{A}^b$	-	0.024	-	$\Omega$
		$V_{GS} = 4.5\ \text{V}$	$I_D = 15\ \text{A}^b$	-	0.028	-	
Forward Transconductance	$g_{fs}$	$V_{DS} = 25\ \text{V}, I_D = 21\ \text{A}^b$	23	-	-	S	
<b>Dynamic</b>							
Input Capacitance	$C_{iss}$	$V_{GS} = 0\ \text{V},$ $V_{DS} = 25\ \text{V},$ $f = 1.0\ \text{MHz}$ , see fig. 5	-	190	-	pF	
Output Capacitance	$C_{oss}$		-	920	-		
Reverse Transfer Capacitance	$C_{rss}$		-	170	-		
Total Gate Charge	$Q_g$	$V_{GS} = 5.0\ \text{V}$	$I_D = 51\ \text{A}, V_{DS} = 48\ \text{V},$ see fig. 6 and 13 <sup>b</sup>	-	-	66	nC
Gate-Source Charge	$Q_{gs}$			-	-	12	
Gate-Drain Charge	$Q_{gd}$			-	-	43	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 30\ \text{V}, I_D = 51\ \text{A},$ $R_g = 4.6\ \Omega, R_D = 0.56\ \Omega$ , see fig. 10 <sup>b</sup>	-	17	-	ns	
Rise Time	$t_r$		-	230	-		
Turn-Off Delay Time	$t_{d(off)}$		-	2	-		
Fall Time	$t_f$		-	110	-		
Internal Drain Inductance	$L_D$	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	nH
Internal Source Inductance	$L_S$			-	7.5	-	
<b>Drain-Source Body Diode Characteristics</b>							
Continuous Source-Drain Diode Current	$I_S$	MOSFET symbol showing the integral reverse p - n junction diode		-	-	50°	A
Pulsed Diode Forward Current <sup>a</sup>	$I_{SM}$			-	-	200	
Body Diode Voltage	$V_{SD}$	$T_J = 25\text{ }^\circ\text{C}, I_S = 51\ \text{A}, V_{GS} = 0\ \text{V}^b$	-	-	2.5	V	
Body Diode Reverse Recovery Time	$t_{rr}$	$T_J = 25\text{ }^\circ\text{C}, I_F = 51\ \text{A}, di/dt = 100\ \text{A}/\mu\text{s}^b$	-	130	180	ns	
Body Diode Reverse Recovery Charge	$Q_{rr}$		-	0.84	1.3	$\mu\text{C}$	
Forward Turn-On Time	$t_{on}$	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )					

**Notes**

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).  
 b. Pulse width  $\leq 300\ \mu\text{s}$ ; duty cycle  $\leq 2\%$ .  
 c. Current limited by the package, (Die Current = 51 A).

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)





Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage



Fig. 7 - Typical Source-Drain Diode Forward Voltage



Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



Fig. 8 - Maximum Safe Operating Area



Fig. 9 - Maximum Drain Current vs. Case Temperature

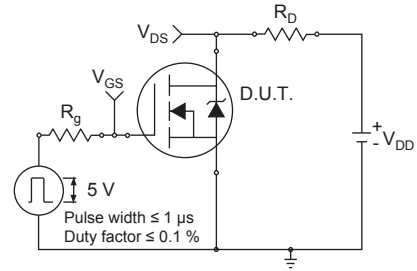


Fig. 10a - Switching Time Test Circuit



Fig. 10b - Switching Time Waveforms



Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

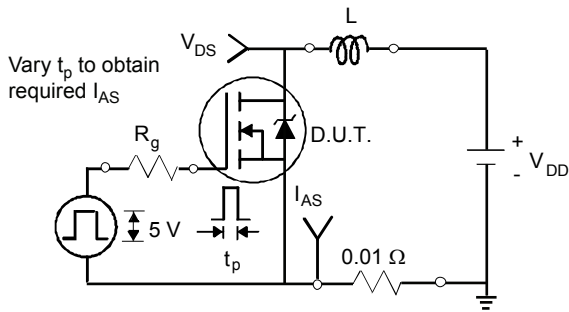


Fig. 12a - Unclamped Inductive Test Circuit



Fig. 12b - Unclamped Inductive Waveforms



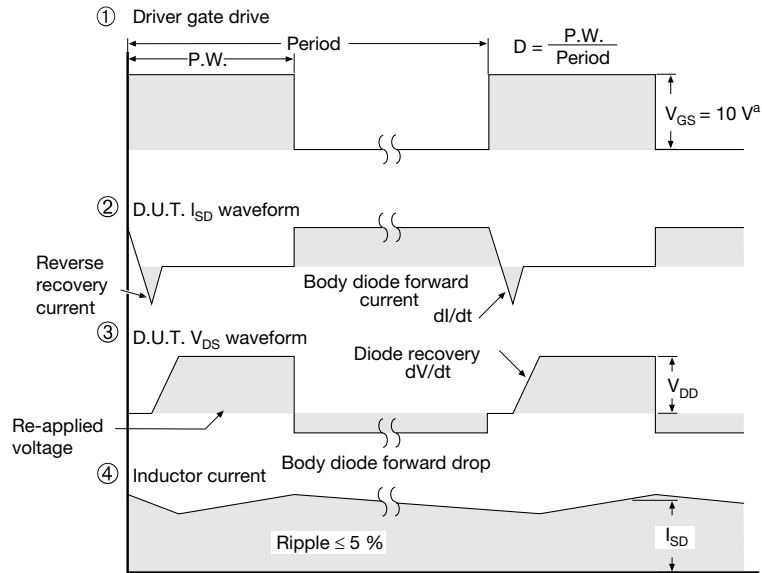
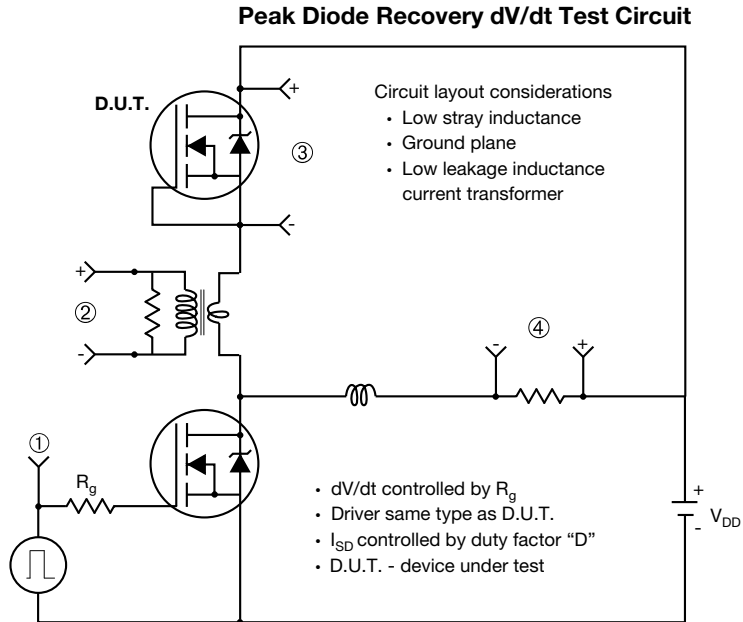
Fig. 12c - Maximum Avalanche Energy vs. Drain Current



Fig. 13a - Basic Gate Charge Waveform



Fig. 13b - Gate Charge Test Circuit

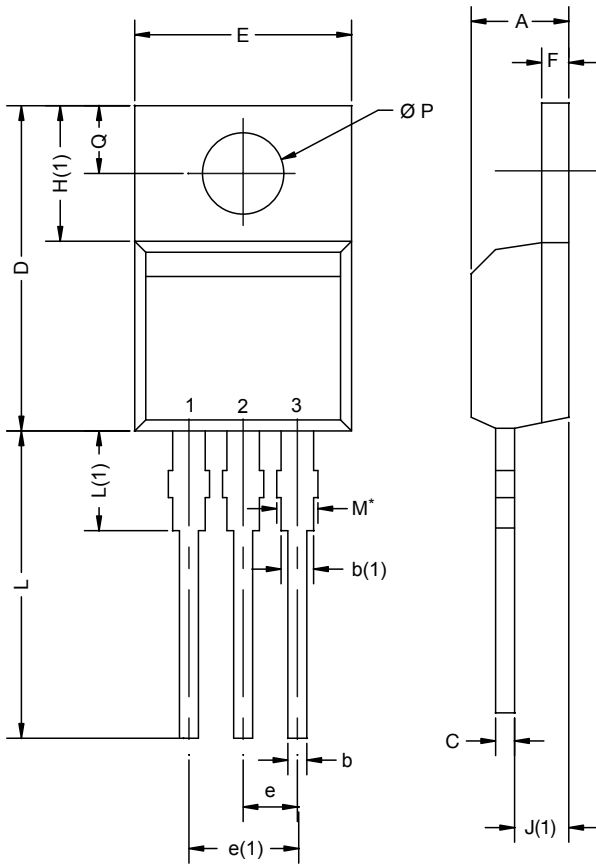


**Note**

a.  $V_{GS} = 5 V$  for logic level devices

**Fig. 14 - For N-Channel**

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DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
c	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
E	10.04	10.51	0.395	0.414
e	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
Ø P	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118

ECN: X12-0208-Rev. N, 08-Oct-12  
DWG: 5471

**Notes**  
\* M = 1.32 mm to 1.62 mm (dimension including protrusion)  
Heatsink hole for HVM



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